May 2013

FSA2257
Low R_{ON}, Low-Voltage Dual SPDT Bi-Directional Analog Switch

Features

- Maximum 1.15 Ω On Resistance (R_{ON}) at 4.5 V V_{CC}
- 0.3 Ω Maximum R_{ON} Flatness at +5 V V_{CC}
- Space-Saving MicroPak™
- Broad V_{CC} Operating Range: 1.65 V to 5.50 V
- Fast Turn-On and Turn-Off Time
- Break-Before-Make Enable Circuitry
- Over-Voltage Tolerant TTL-Compatible Control Input

Applications

- Cell Phone
- PDA
- Mobile Devices

Description

The FSA2257 is a high-performance bi-directional dual Single-Pole/Double-Throw (SPDT) analog switch. This switch can be configured as either a multiplexer or a de-multiplexer by select pins. The device features ultra-low R_{ON} of 1.3 Ω maximum at 4.5 V V_{CC} and operates over the wide V_{CC} range of 1.65 V to 5.50 V. The device is fabricated with submicron CMOS technology to achieve fast switching speeds and is designed for break-before-make operation. The select input is TTL-level compatible.

Ordering Information

Part Number	Package Number	Top Mark	Package Description	Packing Method
FSA2257L10X	MAC10A	EP	10-Lead MicroPak™, 1.6 x 2.1 mm	5000 Units Tape and Reel
FSA2257MTCX	MCT14	FSA2257	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4 mm Wide	2500 Units Tape and Reel
FSA2257MUX	MUA10A	FSA 2257	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0 mm	4000 Units Tape and Reel

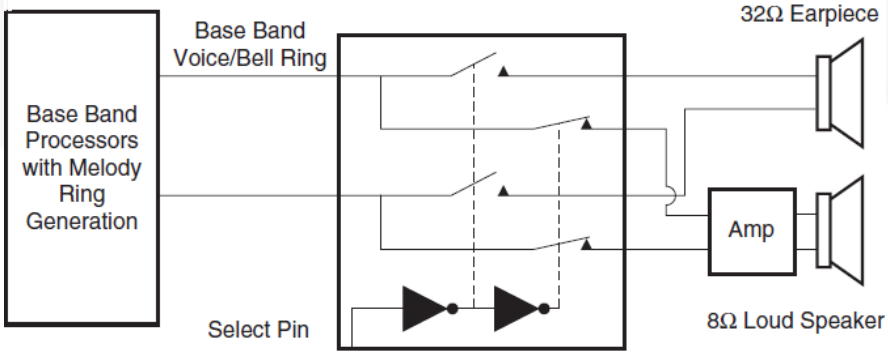


Figure 1. Block Diagram

Pin Configurations

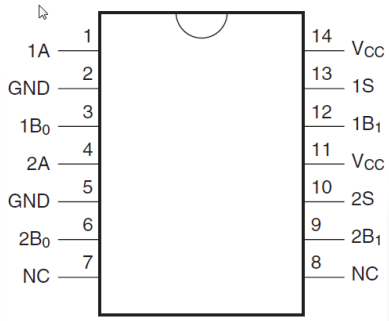


Figure 2. Pin Assignments for TSSOP (Top View)

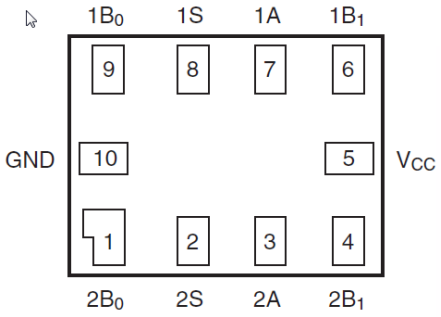


Figure 3. MicroPak™ Pad Assignments (Top View)

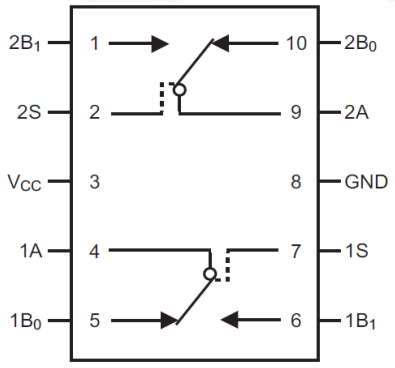


Figure 4. Pin Assignments for MSOP (Top View)

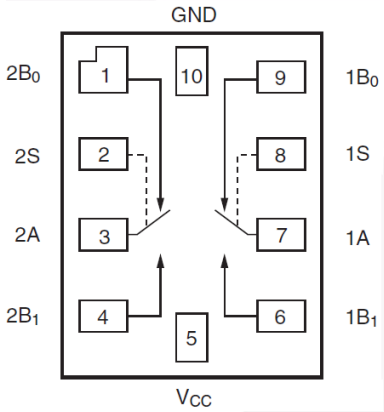


Figure 5. Analog Symbols (Top Through View)

Pin Definitions

Pin# TSSOP	Pin# MicroPak™	Pin # MSOP	Name	Description
1	7	4	1A	Data Ports
2,5	10	8	GND	Ground
3	9	5	$1B_0$	Data Ports
4	3	9	2A	Data Ports
6	1	10	$2B_0$	Data Ports
7,8			NC	No Connect
9	4	1	$2B_1$	Data Ports
10	2	2	2S	Control Inputs
11,14	5	3	V_{CC}	Power Supply
12	6	6	$1B_1$	Data Ports
13	8	7	1S	Control Inputs

Truth Table

Control Input (S)	Function
Low Logic Level	B_0 connected to A
High Logic Level	B_1 connected to A

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.5	6.0	V
V_{SW}	DC Switch Voltage[1]		-0.5	V_{CC} + 0.5	V
V_{IN}	DC Input Voltage[1]		-0.5	6.0	V
I_{IK}	Input Diode Current		-50		mA
	Switch Current			200	
	Peak Switch Current (Pulsed at 1 ms duration, <10% duty cycle)			400	
T_{STG}	Storage Temperature Range		-65	+150	°C
T_J	Maximum Junction Temperature			+150	°C
T_L	Lead Temperature (Soldering, 10 seconds)			+260	°C
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114		8000	V
		Charged Device Model, JESD22-C101		2000	

Note:
1. Input and output negative ratings may be exceeded if input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	1.65	5.50	V
V_{CNTRL}	Control Input Voltage[2]	0	V_{CC}	V
V_{SW}	Switch Input Voltage	0	V_{CC}	V
T_A	Operating Temperature	-40	+85	°C

Note:
2. Unused control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC}(V)	T_A=+25°C			T_A=-40°C to +85°C		Unit
				Min.	Typ.	Max.	Min.	Max.	
V_{IH}	Input Voltage High		1.8 to 2.7				1.0		V
			2.7 to 3.6				2.0		
			4.5 to 5.5				2.4		
V_{IL}	Input Voltage Low		1.8 to 2.7					0.4	V
			2.7 to 3.6					0.6	
			4.5 to 5.5					0.8	
I_{IN}	Control Input Leakage	V_{IN}=0 V to V_{CC}	2.7 to 3.6				-1.0	1.0	µA
			4.5 to 5.5				-1.0	1.0	
$I_{NO(OFF)}$, $I_{NC(OFF)}$	Off Leakage Current of Port B_0 and B_1	A=1 V, 4.5 V, B_0 or B_1=1 V, 4.5 V	5.5	-2		2	-20	20	nA
$I_{A(ON)}$	On Leakage Current of Port A	A=1 V, 4.5V, B_0 or B_1=1 V,4.5 V or Floating	5.5	-4		2	-40	40	nA
R_{ON}	Switch On Resistance MicroPak[3]	I_{OUT}=100 mA, B_0 or B_1=1.5 V	1.8		4.6				Ω
			2.7		2.6	4.0		4.3	
		I_{OUT}=100 mA, B_0 or B_1=3.5 V	4.5		0.95	1.15		1.30	
	Switch On Resistance MSOP/TSSOP[3]	I_{OUT}=100 mA, B_0 or B_1=1.5 V	2.7		2.8			4.5	
		I_{OUT}=100 mA, B_0 or B_1=3.5 V	4.5		1.5			2.3	
ΔR_{ON}	On Resistance Matching Between Channels MicroPak [4]	I_{OUT}=100 mA, B_0 or B_1=3.5 V	4.5		0.06	0.12		0.15	Ω
	On Resistance Matching Between Channels MSOP / TSSOP[4]		4.5		0.7			0.3	
$R_{FLAT(ON)}$	On Resistance Flatness[5]	I_{OUT}=100 mA, B_0 or B_I =0 V, 0.75 V,1.5 V	1.8		3.0				Ω
			2.7		1.4				
		I_{OUT}=100 mA, B_0 or B_I =0 V, 1 V, 2 V	4.5		0.2	0.3		0.4	
I_{CC}	Quiescent Supply Current	V_{IN}=0 V or V_{CC}, I_{OUT}=0 V	3.6		0.1	0.5		1.0	µA
			5.5		0.1	0.5		1.0	

Notes:

3. On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
4. $\Delta R_{ON} = R_{ONmax} – R_{ONmin}$ measured at identical V_{CC}, temperature, and voltage.
5. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

AC Electrical Characteristics

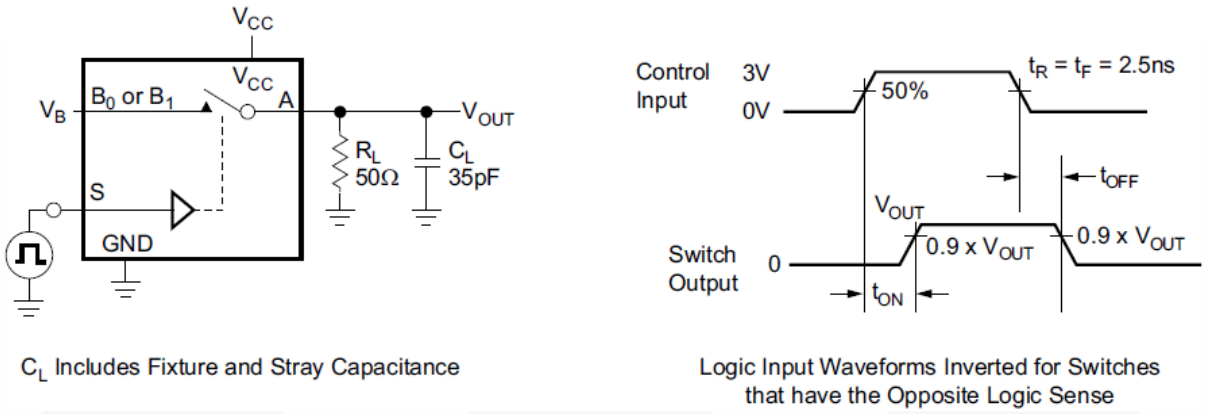
Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V_{CC}(V)	T_A=+25°C			T_A=-40°C to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t_{ON}	Turn-On Time	B_0 or B_1=1.5 V, R_L=50 Ω, C_L=35 pF	1.8 to 2.7		75				ns	Figure 6
			2.7 to 3.6			50		60		
		B_0 or B_1=3.0 V, R_L=50 Ω, C_L=35 pF	4.5 to 5.5			35		40		
t_{OFF}	Turn-Off Time	B_0 or B_1=1.5 V, R_L=50 Ω, C_L=35 pF	1.8 to 2.7		20				ns	Figure 6
			2.7 to 3.6			20		30		
		B_0 or B_1=3.0 V, R_L=50 Ω, C_L=35 pF	4.5 to 5.5			15		20		
t_{BBM}	Break-Before-Make Time	B_0 or B_1=1.5 V, R_L=50 Ω, C_L=35 pF	2.7 to 3.6				1		ns	Figure 7
		B_0 or B_1=3.0 V, R_L=50 Ω, C_L=35 pF	4.5 to 5.5		20		1			
Q	Charge Injection	C_L=1.0 nF, V_{GEN}=0 V, R_{GEN}=0 Ω	2.7 to 3.6		20				pC	Figure 9
			4.5 to 5.5		10					
OIRR	Off Isolation	f=1 MHz, R_L=50 Ω	2.7 to 3.6		-70				dB	Figure 8
			4.5 to 5.5		-70					
Xtalk	Crosstalk	f=1 MHz, R_L=50 Ω	2.7 to 3.6		-75				dB	Figure 8
			4.5 to 5.5		-75					
BW	-3 db Bandwidth	R_L=50 Ω	2.7 to 3.6		200				MHz	Figure 11
			4.5 to 5.5		200					
THD	Total Harmon Distortion	R_L=600 Ω, V_{IN}=0.5 V_{PP} f=20 Hz to 20 kHz	2.7 to 3.6		0.002				%	Figure 12
			4.5 to 5.5		0.002					

Capacitance

Symbol	Parameter	Conditions	V_{CC} (V)	T_A=+25°C			Unit	Figure
				Min.	Typ.	Max.		
C_{IN}	Control Pin Input Capacitance	f=1 MHz	0		3.5		pF	Figure 10
C_{OFF}	B Port Off Capacitance	f=1 MHz	4.5		12.0		pF	Figure 10
C_{ON}	A Port On Capacitance	f=1 MHz	4.5		40.0		pF	Figure 10

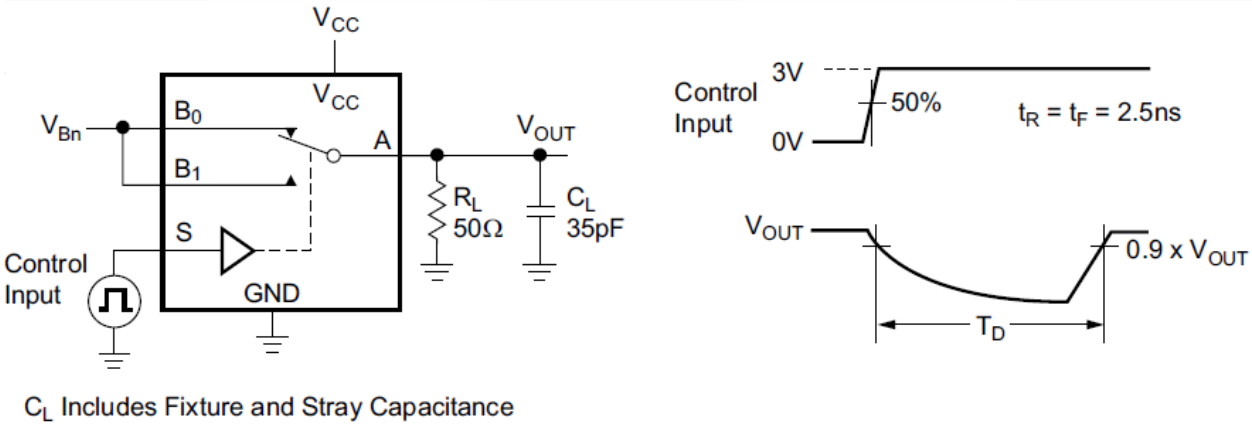
AC Loadings and Waveforms



C_L Includes Fixture and Stray Capacitance

Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 6. Turn On / Off Timing



C_L Includes Fixture and Stray Capacitance

Figure 7. Break Before Make Timing

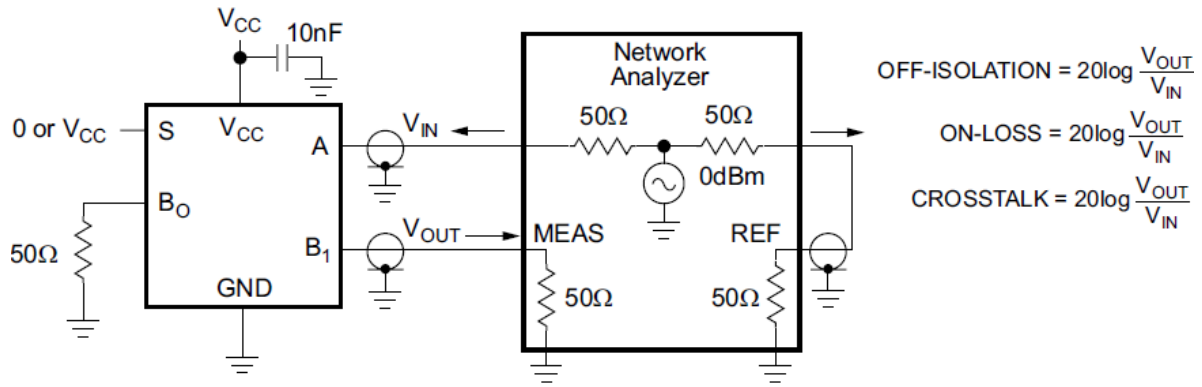


Figure 8. Off Isolation and Crosstalk

AC Loadings and Waveforms (Continued)

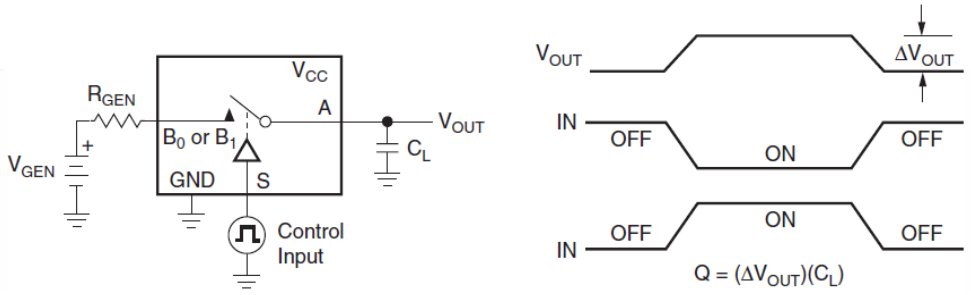


Figure 9. Charge Injection

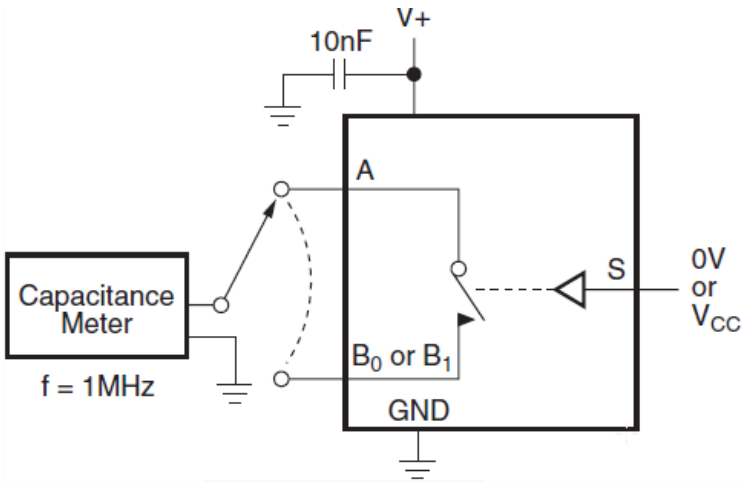


Figure 10. On / Off Capacitance Measurement Setup

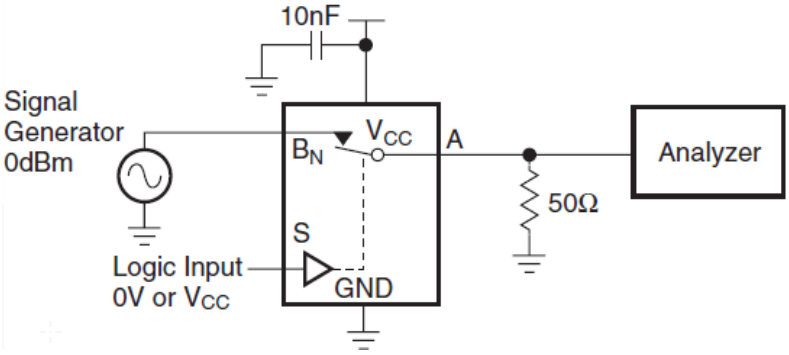


Figure 11. Bandwidth

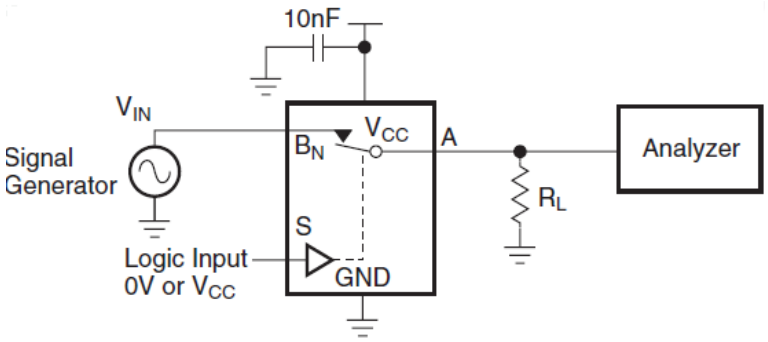
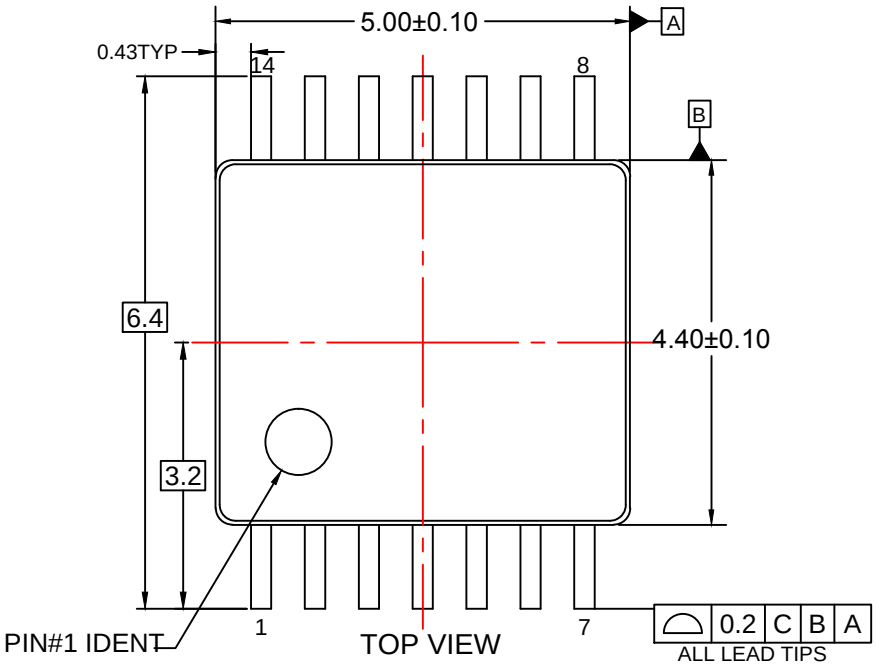
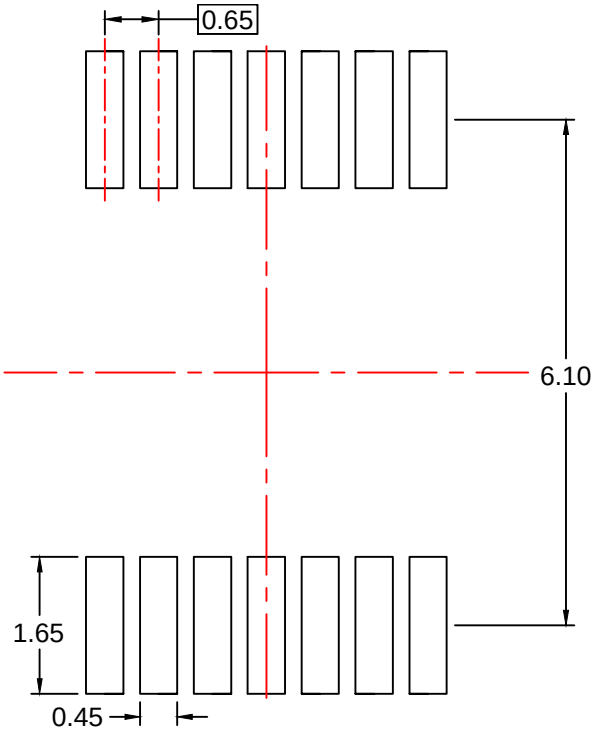


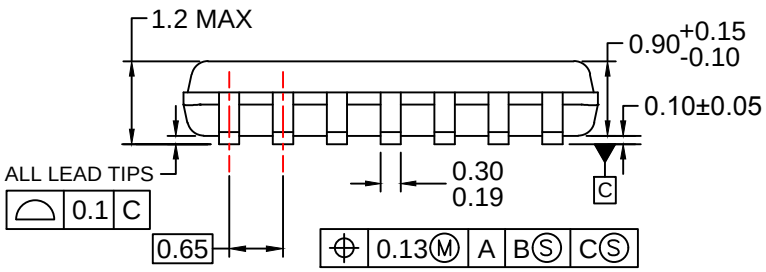
Figure 12. Harmonic Distortion



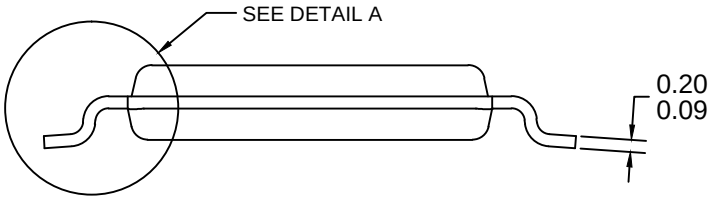
TOP VIEW

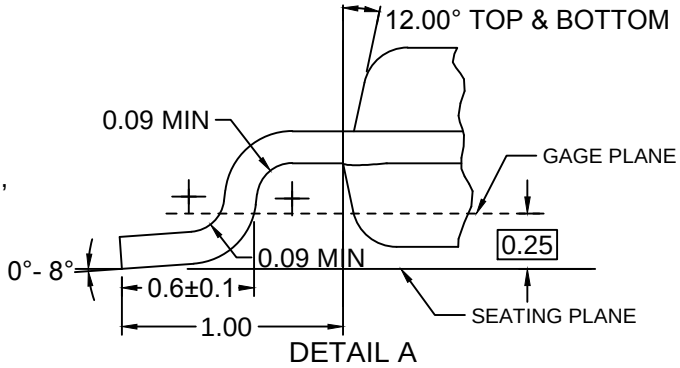


RECOMMENDED LAND PATTERN



FRONT VIEW





DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6

B. DIMENSIONS ARE IN MILLIMETERS.

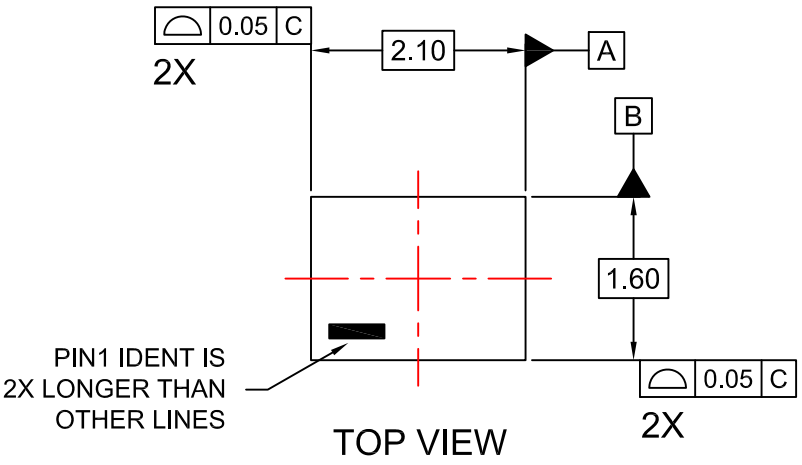
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 2009.

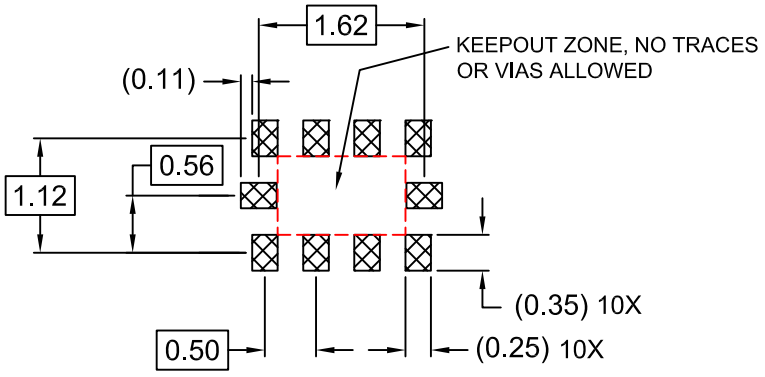
E. LANDPATTERN STANDARD: SOP65P640X110-14M.

F. DRAWING FILE NAME: MKT-MTC14rev7.

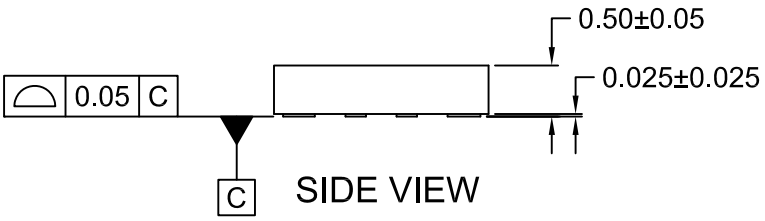
FAIRCHILD



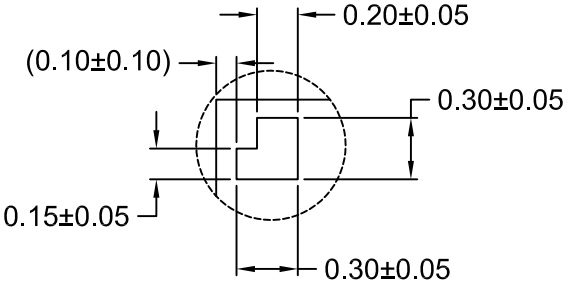
TOP VIEW



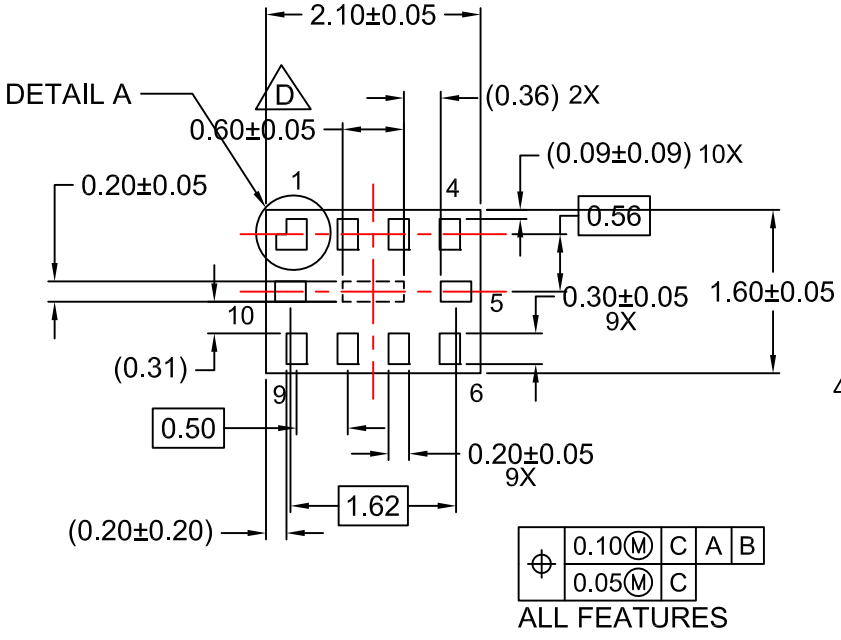
RECOMMENDED LAND PATTERN



SIDE VIEW



DETAIL A 2X SCALE



BOTTOM VIEW

NOTES:

A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD .

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

D. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.

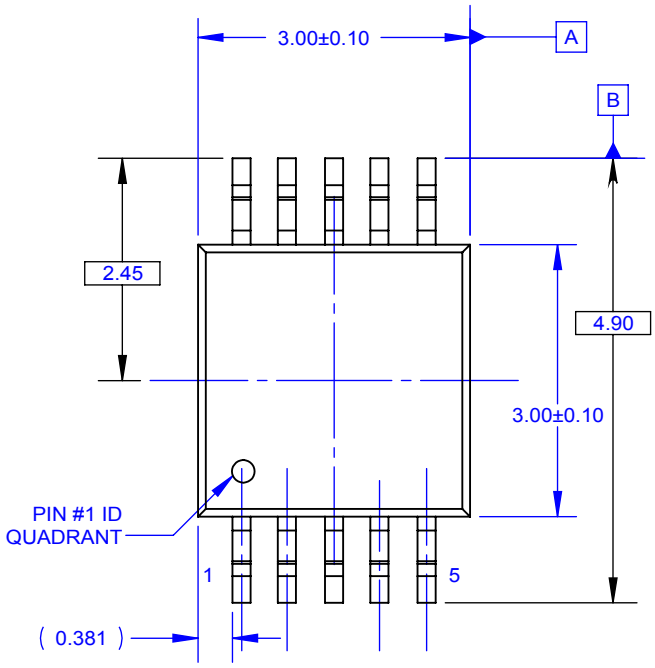
E. DRAWING FILENAME: MKT-MAC10Arev6.

F. DIMENSIONS WITHIN ( ) ARE UNCONTROLLED

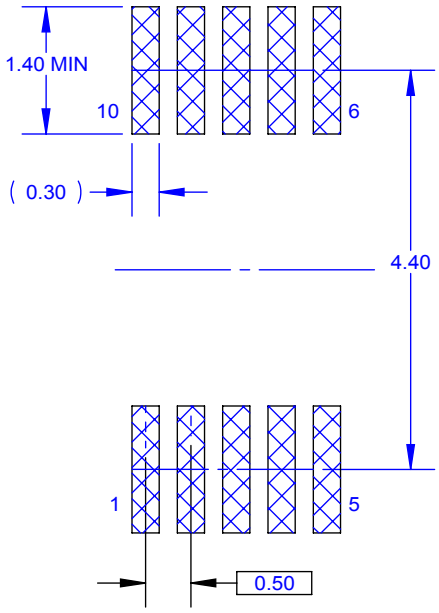
FAIRCHILD

REVISIONS

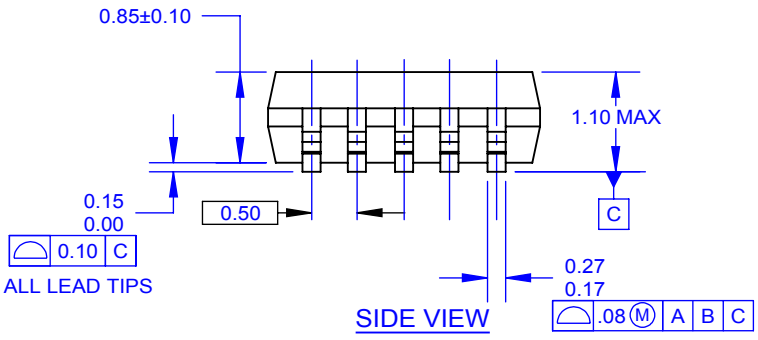
NBR	DESCRIPTION	DATE	BY/APP'D
B	REDREW FORMER NSC DWG	07JUN2006	H.ALLEN
2	* REMOVE SITE ADDRESS AND CHANGE REVISION TO NUMERICAL & CHANGED LAND PATTERN TO IPC. * CHANGE LEAD WIDTH FROM 0.27MAX TO 0.33MAX. * REMOVE DATE OF JEDEC REVISION	20AUG2009	KHLEE/FSSZ
3	* REVERT LEAD WIDTH TO 0.27MAX.	24SEP2009	KHLEE/FSSZ



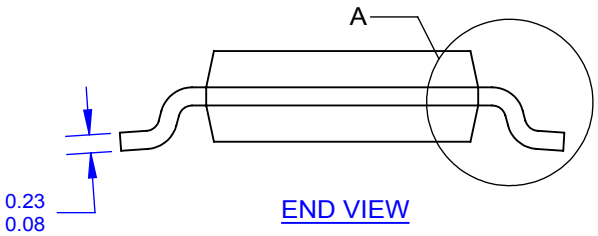
TOP VIEW



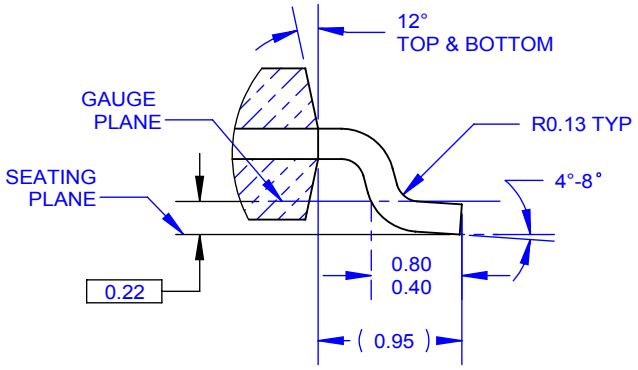
LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW



DETAIL A
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

A. THIS PACKAGE CONFORMS TO JEDEC MO-187 VARIATION BA.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
E. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN
F. FILE NAME: MKT-MUA10AREV3

APPROVALS	DATE
DRAWN: BOBOY MALDO	24SEP09
CHECKED: KH LEE	
APPROVED: BY HUANG	
APPROVED: HOWARD ALLEN	

PROJECTION [MM] INCH

FAIRCHILD SEMICONDUCTOR TM

10LD, MSOP, JEDEC MO-187, 3.0MM WIDE

SCALE	SIZE	DRAWING NUMBER	REV
1:1	N/A	MKT-MUA10A	3

FORMERLY: N/A

SHEET : 1 OF 1

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™
AttitudeEngine™
Awinda®
AX-CAP®*
BitSiC™
Build it Now™
CorePLUS™
CorePOWER™
CROSSVOLT™
CTL™
Current Transfer Logic™
DEUXPEED®
Dual Cool™
EcoSPARK®
EfficientMax™
ESBC™
Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FastvCore™
FETBench™
FPS™
F-PFS™
FRFET®
Global Power Resource SM
GreenBridge™
Green FPS™
Green FPS™ e-Series™
G*max*™
GTO™
IntelliMAX™
ISOPLANAR™
Making Small Speakers Sound Louder and Better™
MegaBuck™
MICROCOUPLER™
MicroFET™
MicroPak™
MicroPak2™
MillerDrive™
MotionMax™
MotionGrid®
MTi®
MTx®
MVN®
mWSaver®
OptoHiT™
OPTOLOGIC®
OPTOPLANAR®
®
Power Supply WebDesigner™
PowerTrench®
PowerXS™
Programmable Active Droop™
QFET®
QS™
Quiet Series™
RapidConfigure™
™
Saving our world, 1mW/W/kW at a time™
SignalWise™
SmartMax™
SMART START™
Solutions for Your Success™
SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™
SYSTEM GENERAL®*
TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®*
µSerDes™
SerDes™
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
Xsens™
仙童®

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT HTTP://WWW.FAIRCHILDSEMI.COM. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

AUTHORIZED USE

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I77